



DOCKET NO.: CHITTIPEDDI 59-108

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PATENT

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Sailish Chittipeddi, *et al.*

Serial No.: 09/467,253

Filed: December 20, 1999

For: WIRE BONDING METHOD FOR COPPER INTERCONNECTS
IN SEMICONDUCTOR DEVICES

Group No.: 2823

Examiner: Estrada, Michelle

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

CERTIFICATE OF MAILING
I hereby certify that this correspondence is being deposited with the United States Postal Service as first
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Sir:

REQUEST FOR RECONSIDERATION UNDER 37 C.F.R. § 1.111

In response to the Office Action mailed February 25, 2003, please accept the following
remarks:

RECEIVED
MAY 23 2003
TECHNOLOGY CENTER 2800